Features

- Fast Read Access Time 55 ns
- Low Power CMOS Operation
 - 100 μA max. Standby
 - 25 mA max. Active at 5 MHz
- JEDEC Standard Packages
 - 32-Lead 600-mil PDIP
 - 32-Lead PLCC
 - 32-Lead TSOP
- 5V ± 10% Supply
- High-Reliability CMOS Technology
 - 2,000V ESD Protection
 - 200 mA Latchup Immunity
- Rapid[™] Programming Algorithm 100 µs/byte (typical)
- CMOS and TTL Compatible Inputs and Outputs
- Integrated Product Identification Code
- Commercial and Industrial Temperature Ranges

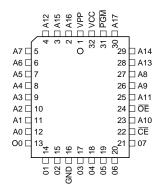
Description

The AT27C020 is a low-power, high performance 2,097,152-bit one-time programmable read only memory (OTP EPROM) organized as 256K by 8 bits. It requires only one 5V power supply in normal read mode operation. Any byte can be accessed in less than 55 ns, eliminating the need for speed reducing WAIT states on high performance microprocessor systems. *(continued)*

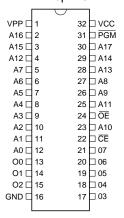
Pin Configurations

Pin Name	Function
A0 - A17	Addresses
O0 - O7	Outputs
CE	Chip Enable
ŌĒ	Output Enable
PGM	Program Strobe

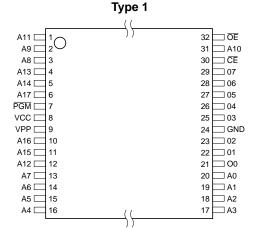
PLCC Top View



PDIP Top View



TSOP Top View





2-Megabit (256K x 8) OTP EPROM

AT27C020

Rev. 0570C-01/98





In read mode, the AT27C020 typically consumes 8 mA. Standby mode supply current is typically less than 10 μ A.

The AT27C020 is available in a choice of industry standard JEDEC-approved one-time programmable (OTP) plastic PDIP, PLCC, and TSOP packages. All devices feature two-line control (\overline{CE} , \overline{OE}) to give designers the flexibility to prevent bus contention.

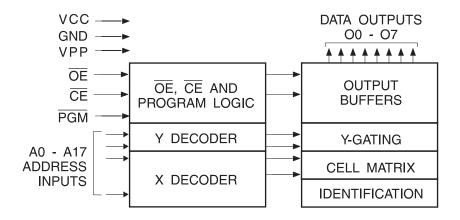
With 256K byte storage capability, the AT27C020 allows firmware to be stored reliably and to be accessed by the system without the delays of mass storage media.

Atmel's 27C020 have additional features to ensure high quality and efficient production use. The Rapid™ Programming Algorithm reduces the time required to program the part and guarantees reliable programming. Programming time is typically only 100 µs/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry standard programming equipment to select the proper programming algorithms and voltages.

System Considerations

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed data sheet limits, resulting in device non-conformance. At a minimum, a 0.1 μF high frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V_{CC} and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a 4.7 μF bulk electrolytic capacitor should be utilized, again connected between the V_{CC} and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

Block Diagram



Absolute Maximum Ratings*

Temperature Under Bias	55°C to +125°C
Storage Temperature	65°C to +150°C
Voltage on Any Pin with Respect to Ground	2.0V to +7.0V ⁽¹⁾
Voltage on A9 with Respect to Ground	2.0V to +14.0V ⁽¹⁾
V _{PP} Supply Voltage with Respect to Ground	2.0V to +14.0V ⁽¹⁾

*NOTICE: Stresses beyond those listed under "Absolute

Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device

reliability.

Note: 1. Minimum voltage is -0.6V DC which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is $V_{CC} + 0.75V$ DC which may overshoot to +7.0V for pulses of less than 20 ns.

Operating Modes

Mode/Pin	CE	ŌĒ	PGM	Ai	V _{PP}	Outputs
Read	V _{IL}	V _{IL}	X ⁽¹⁾	Ai	Х	D _{OUT}
Output Disable	Х	V _{IH}	Х	X	Х	High Z
Standby	V _{IH}	Х	Х	X	Х	High Z
Rapid Program ⁽²⁾	V _{IL}	V _{IH}	V _{IL}	Ai	V _{PP}	D _{IN}
PGM Verify	V_{IL}	V _{IL}	V _{IH}	Ai	V _{PP}	D _{OUT}
PGM Inhibit	V _{IH}	Х	Х	X	V _{PP}	High Z
Product Identification ⁽⁴⁾	V _{IL}	V _{IL}	х	$A9 = V_{H}^{(3)}$ $A0 = V_{IH} \text{ or } V_{IL}$ $A1 - A17 = V_{IL}$	х	Identification Code

Notes: 1. X can be V_{IL} or V_{IH}.

- 2. Refer to Programming Characteristics.
- 3. $V_H = 12.0 \pm 0.5 V$.
- 4. Two identifier bytes may be selected. All Ai inputs are held low (V_{IL}), except A9 which is set to V_H and A0 which is toggled low (V_{IL}) to select the Manufacturer's Identification byte and high (V_{IH}) to select the Device Code byte.





DC and AC Operating Conditions for Read Operation

				AT27C020		
		-55	-70	-90	-12	-15
Operating	Com.	0°C - 70°C				
Temperature (Case)	Ind.	-40°C - 85C				
V _{CC} Power Supply	·	5V ± 10%				

DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition	Min	Max	Units
I _{LI}	Input Load Current	$V_{IN} = 0V$ to V_{CC} (Com., Ind.)		±1.0	μΑ
I _{LO}	Output Leakage Current	V _{OUT} = 0V to V _{CC} (Com., Ind.)		±5.0	μΑ
I _{PP} ⁽²⁾	V _{PP} ⁽¹⁾ Read/Standby Current	$V_{PP} = V_{CC}$		±10	μΑ
	V (1) Chandley Comment	I_{SB1} (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		100	μΑ
I _{SB}	V _{CC} ⁽¹⁾ Standby Current	I_{SB2} (TTL), \overline{CE} = 2.0 to V_{CC} + 0.5V		1.0	mA
I _{CC}	V _{CC} Active Current	$f = 5 \text{ MHz}, I_{OUT} = 0 \text{ mA}, \overline{CE} = V_{IL}$		25	mA
V _{IL}	Input Low Voltage		-0.6	0.8	V
V _{IH}	Input High Voltage		2.0	V _{CC} + 0.5	V
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		0.4	V
V _{OH}	Output High Voltage	I _{OH} = -400 μA	2.4		V

Notes: 1. V_{CC} must be applied simultaneously or before V_{PP} , and removed simultaneously or after V_{PP} .

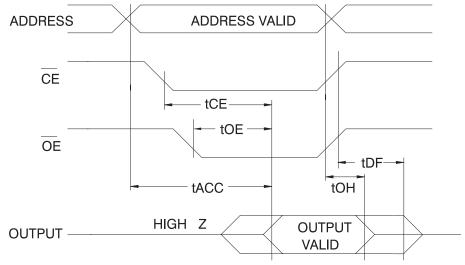
2. V_{PP} may be connected directly to V_{CC} except during programming. The supply current would then be the sum of I_{CC} and I_{PP} .

AC Characteristics for Read Operation

			AT27C020										
			-;	55	-	70	-(90		12		15	
Symbol	Parameter	Condition	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Units
t _{ACC} ⁽³⁾	Address to Output Delay	CE = OE = V _{IL}		55		70		90		120		150	ns
t _{CE} ⁽²⁾	CE to Output Delay	OE = V _{IL}		55		70		90		120		150	ns
t _{OE} ⁽²⁾⁽³⁾	OE to Output Delay	CE = V _{IL}		20		30		35		35		40	ns
t _{DF} ⁽⁴⁾⁽⁵⁾	OE or CE High to Output Float, whichever occurred first			18		20		20		30		40	ns
t _{OH}	Output Hold from Address, CE or OE, whichever occurred first		7		7		0		0		0		ns

Note: 2, 3, 4, 5. See AC Waveforms for Read Operation diagram.

AC Waveforms for Read Operation(1)

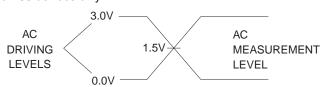


Notes: 1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.

- 2. $\overline{\text{OE}}$ may be delayed up to t_{CE} t_{OE} after the falling edge of $\overline{\text{CE}}$ without impact on t_{CE} .
- 3. $\overline{\text{OE}}$ may be delayed up to t_{ACC} t_{OE} after the address is valid without impact on t_{ACC} .
- 4. This parameter is only sampled and is not 100% tested.
- 5. Output float is defined as the point when data is no longer driven.

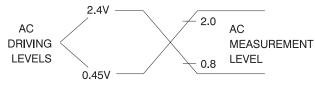
Input Test Waveforms and Measurement Levels

For -55 devices only:



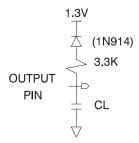
 t_R , $t_F < 5$ ns (10% to 90%)

For -70,-90,-12,-15 devices only:



 t_R , t_F < 20 ns (10% to 90%)

Output Test Load



Note: CL = 100 pF including jig capacitance except -55 devices where CL = 30 pF.

Pin Capacitance

 $f = 1 \text{ MHz}, T = 25^{\circ}C^{(1)}$

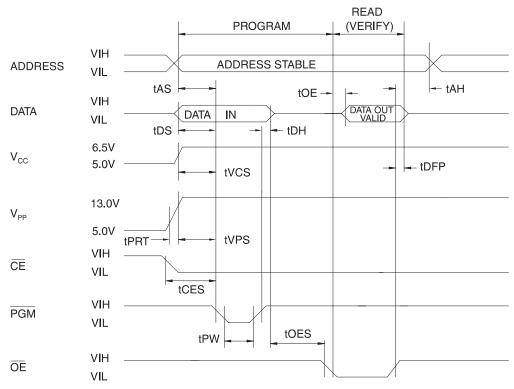
Symbol	Тур	Max	Units	Conditions
C _{IN}	4	8	pF	V _{IN} = 0V
C _{OUT}	8	12	pF	V _{OUT} = 0V

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.





Programming Waveforms (1)



Notes: 1. The Input Timing reference is 0.8V for $V_{\rm IL}$ and 2.0V for $V_{\rm IH}$.

- 2. t_{OE} and t_{DFP} are characteristics of the device but must be accommodated by the programmer.
- 3. When programming the AT27C020, a 0.1 μF capacitor is required across V_{PP} and ground to suppress voltage transients.

DC Programming Characteristics

 $T_A = 25 \pm 5$ °C, $V_{CC} = 6.5 \pm 0.25$ V, $V_{PP} = 13.0 \pm 0.25$ V

			Li	mits		
Symbol	Parameter	Test Conditions	Min	Max	Units	
ILI	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		±10	μΑ	
V_{IL}	Input Low Level		-0.6	0.8	V	
V _{IH}	Input High Level		2.0	V _{CC} + 1.0	V	
V _{OL}	Output Low Voltage	I _{OL} = 2.1 mA		0.4	V	
V _{OH}	Output High Voltage	I _{OH} = -400 μA	2.4		V	
I _{CC2}	V _{CC} Supply Current (Program and Verify)			40	mA	
I _{PP2}	V _{PP} Supply Current	CE = PGM = V _{IL}		20	mA	
V _{ID}	A9 Product Identification Voltage		11.5	12.5	V	

AC Programming Characteristics

 $T_A = 25 \pm 5^{\circ}C$, $V_{CC} = 6.5 \pm 0.25V$, $V_{PP} = 13.0 \pm 0.25V$

			Lir	mits	
Symbol	Parameter	Test Condition (1)	Min	Max	Units
t _{AS}	Address Setup Time		2		μs
t _{CES}	CE Setup Time		2		μs
t _{OES}	OE Setup Time	Input Rise and Fall Times:	2		μs
t _{DS}	Data Setup Time	(10% to 90%) 20 ns	2		μs
t _{AH}	Address Hold Time	Input Pulse Levels:	0		μs
t _{DH}	Data Hold Time	0.45V to 2.4V	2		μs
t _{DFP}	OE High to Output Float Delay ⁽²⁾		0	130	ns
t _{VPS}	V _{PP} Setup Time	Input Timing Reference Level: 0.8V to 2.0V	2		μs
t _{VCS}	V _{CC} Set up Time	0.37 10 2.07	2		μs
t _{PW}	PGM Program Pulse Width ⁽³⁾	Output Timing Reference Level:	95	105	μs
t _{OE}	Data Valid from OE	0.8V to 2.0V		150	ns
t _{PRT}	V _{PP} Pulse Rise Time During Programming		50		ns

Notes: 1. V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP} .

2. This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven — see timing diagram.

3. Program Pulse width tolerance is 100 $\mu s \pm 5\%$.

Atmel's 27C020 Integrated Product Identification Code

		Pins								
Codes	A0	07	06	O5	04	О3	O2	01	00	Hex Data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device Type	1	1	0	0	0	0	1	1	0	86

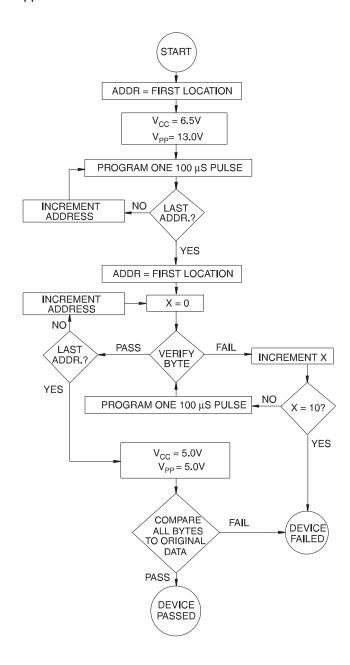




Rapid Programming Algorithm

A 100 μ s \overline{PGM} pulse width is used to program. The address is set to the first location. V_{CC} is raised to 6.5V and V_{PP} is raised to 13.0V. Each address is first programmed with one 100 μ s \overline{PGM} pulse without verification. Then a verification / reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100 μ s pulses are applied with a verification

after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked. V_{PP} is then lowered to 5.0V and V_{CC} to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.



Ordering Information

t _{ACC}	I _{cc}	(mA)			
(ns)	Active	Standby	Ordering Code	Package	Operation Range
55	25	0.1	AT27C020-55JC AT27C020-55PC AT27C020-55TC	32J 32P6 32T	Commercial (0°C to 70°C)
	25	0.1	AT27C020-55JI AT27C020-55PI AT27C020-55TI	32J 32P6 32T	Industrial (-40°C to 85°C)
70	25	0.1	AT27C020-70JC AT27C020-70PC AT27C020-70TC	32J 32P6 32T	Commercial (0°C to 70°C)
	25	0.1	AT27C020-70JI AT27C020-70PI AT27C020-70TI	32J 32P6 32T	Industrial (-40°C to 85°C)
90	25	0.1	AT27C020-90JC AT27C020-90PC AT27C020-90TC	32J 32P6 32T	Commercial (0°C to 70°C)
	25	0.1	AT27C020-90JI AT27C020-90PI AT27C020-90TI	32J 32P6 32T	Industrial (-40°C to 85°C)
120	25	0.1	AT27C020-12JC AT27C020-12PC AT27C020-12TC	32J 32P6 32T	Commercial (0°C to 70°C)
	25	0.1	AT27C020-12JI AT27C020-12PI AT27C020-12TI	32J 32P6 32T	Industrial (-40°C to 85°C)
150	25	0.1	AT27C020-15JC AT27C020-15PC AT27C020-15TC	32J 32P6 32T	Commercial (0°C to 70°C)
	25	0.1	AT27C020-15JI AT27C020-15PI AT27C020-15TI	32J 32P6 32T	Industrial (-40°C to 85°C)

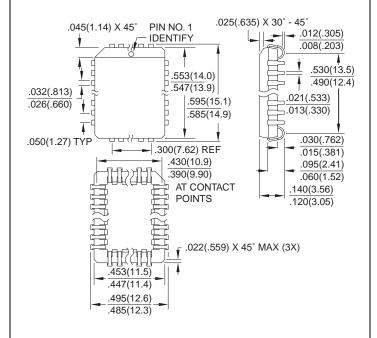
	Package Type					
32J	32-Lead,Plastic J-Leaded Chip Carrier (PLCC)					
32P6	32-Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)					
32T	32-Lead, Plastic Thin Small Outline Package (TSOP)					





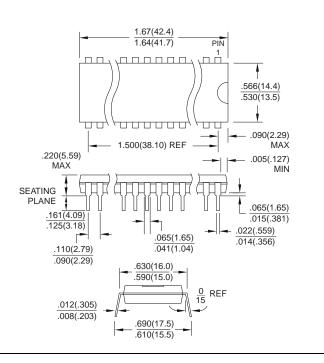
Packaging Information

32J, 32-Lead, Plastic J-Leaded Chip Carrier (PLCC) Dimensions in Inches and (Millimeters)
JEDEC STANDARD MS-016 AE



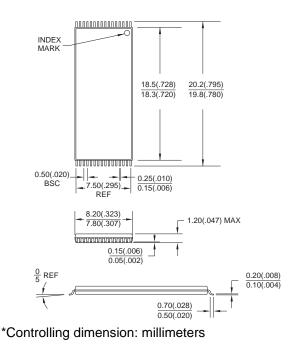
32P6, 32-Lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)

Dimensions in Inches and (Millimeters)



32T, 32-Lead, Plastic Thin Small Outline Package (TSOP)

Dimensions in Millimeters and (Inches)*
JEDEC OUTLINE MO-142 BD







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